

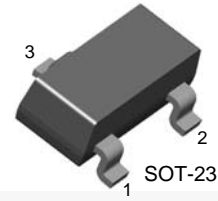


October 2014

## BC846 / BC847 / BC848 / BC850 NPN Epitaxial Silicon Transistor

### Features

- Switching and Amplifier Applications
- Suitable for Automatic Insertion in Thick and Thin-film Circuits
- Low Noise: BC850
- Complement to BC856, BC857, BC858, BC859, and BC860



1. Base 2. Emitter 3. Collector

### Ordering Information<sup>(1)</sup>

Part Number	Marking	Package	Packing Method
BC846AMTF	8AA	SOT-23 3L	Tape and Reel
BC846BMTF	8AB	SOT-23 3L	Tape and Reel
BC846CMTF	8AC	SOT-23 3L	Tape and Reel
BC847AMTF	8BA	SOT-23 3L	Tape and Reel
BC847BMTF	8BB	SOT-23 3L	Tape and Reel
BC847CMTF	8BC	SOT-23 3L	Tape and Reel
BC848BMTF	8CB	SOT-23 3L	Tape and Reel
BC848CMTF	8CC	SOT-23 3L	Tape and Reel
BC850AMTF	8EA	SOT-23 3L	Tape and Reel
BC850CMTF	8EC	SOT-23 3L	Tape and Reel

#### Note:

1. Affix "-A,-B,-C" means  $h_{FE}$  classification. Affix "-M" means SOT-23 package. Affix "-TF" means the tape and reel type packing.

BC846 / BC847 / BC848 / BC850 — NPN Epitaxial Silicon Transistor

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$V_{CBO}$	Collector-Base Voltage	BC846	80
		BC847 / BC850	50
		BC848	30
$V_{CEO}$	Collector-Emitter Voltage	BC846	65
		BC847 / BC850	45
		BC848	30
$V_{EBO}$	Emitter-Base Voltage	BC846 / BC847	6
		BC848 / BC850	5
$I_C$	Collector Current (DC)	100	mA
$T_J$	Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-65 to +150	$^\circ\text{C}$

## Thermal Characteristics<sup>(2)</sup>

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$P_D$	Power Dissipation	310	mW
	Derate Above $25^\circ\text{C}$	2.48	mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	403	$^\circ\text{C}/\text{W}$

### Note:

2. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

**Electrical Characteristics<sup>(3)</sup>**Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
$I_{CBO}$	Collector Cut-Off Current	$V_{CB} = 30\text{ V}, I_E = 0$			15	nA	
$h_{FE}$	DC Current Gain	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	110		800		
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 10\text{ mA}, I_B = 0.5\text{ mA}$		90	250	mV	
		$I_C = 100\text{ mA}, I_B = 5\text{ mA}$		200	600		
$V_{BE(sat)}$	Collector-Base Saturation Voltage	$I_C = 10\text{ mA}, I_B = 0.5\text{ mA}$		700		mV	
		$I_C = 100\text{ mA}, I_B = 5\text{ mA}$		900			
$V_{BE(on)}$	Base-Emitter On Voltage	$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	580	660	700	mV	
		$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}$			720		
$f_T$	Current Gain Bandwidth Product	$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}, f = 100\text{ MHz}$		300		MHz	
$C_{ob}$	Output Capacitance	$V_{CB} = 10\text{ V}, I_E = 0, f = 1\text{ MHz}$		3.5	6.0	pF	
$C_{ib}$	Input Capacitance	$V_{EB} = 0.5\text{ V}, I_C = 0, f = 1\text{ MHz}$		9		pF	
NF	Noise Figure	BC846 / BC847 / BC848	$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega, f = 1\text{ kHz}$		2.0	10.0	dB
		BC850			1.2	4.0	
		BC850		$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega, f = 30\text{ to }15000\text{ Hz}$		1.4	

**Note:**3. Pulse test: pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$  **$h_{FE}$  Classification**

Classification	A	B	C
$h_{FE}$	110 ~ 220	200 ~ 450	420 ~ 800

## Typical Performance Characteristics

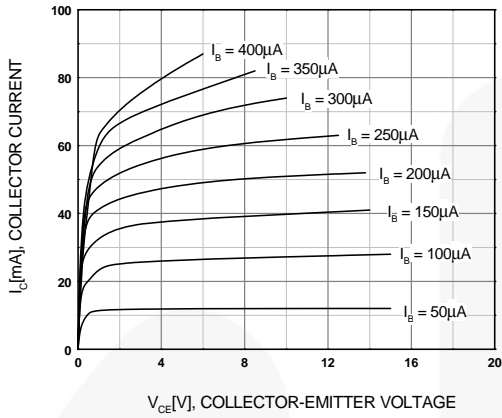


Figure 1. Static Characteristic

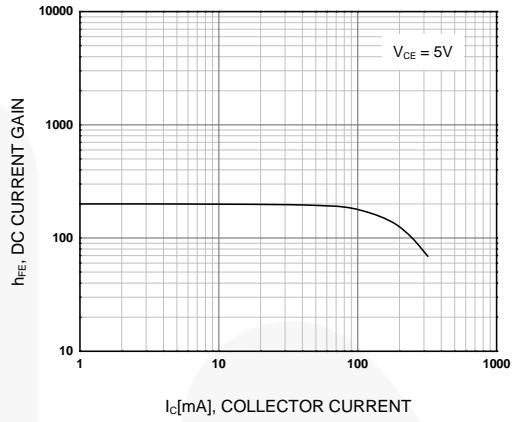


Figure 2. DC Current Gain

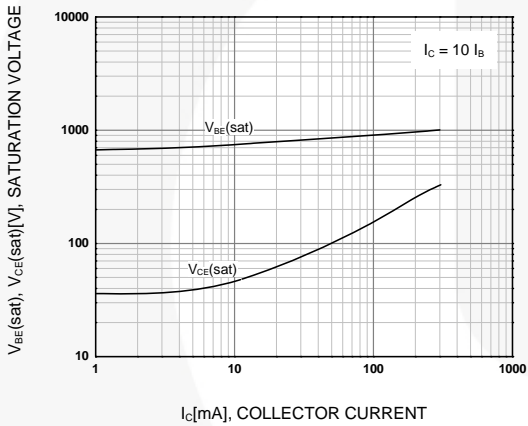


Figure 3. Base-Emitter Saturation Voltage and Collector-Emitter Saturation Voltage

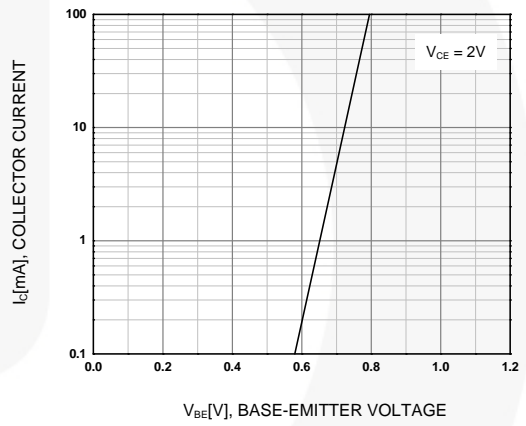


Figure 4. Base-Emitter On Voltage

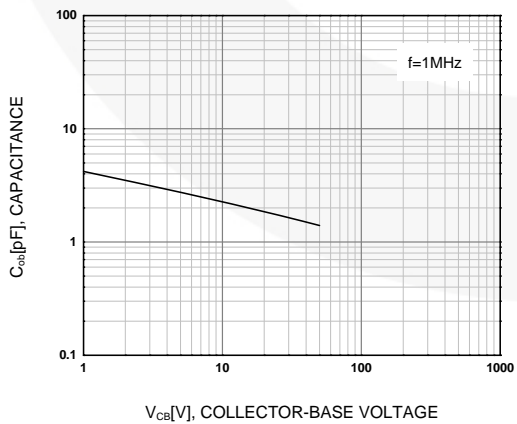


Figure 5. Collector Output Capacitance

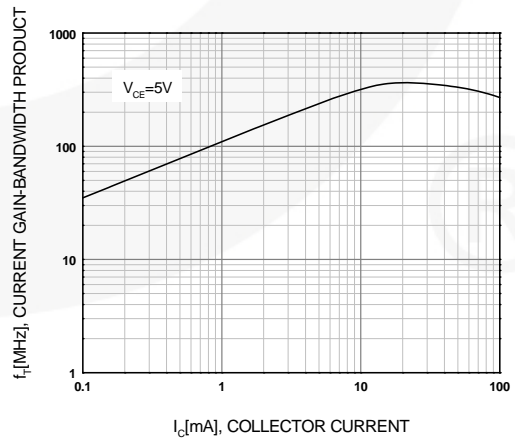
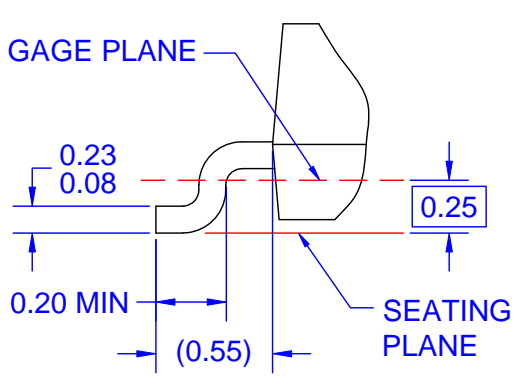
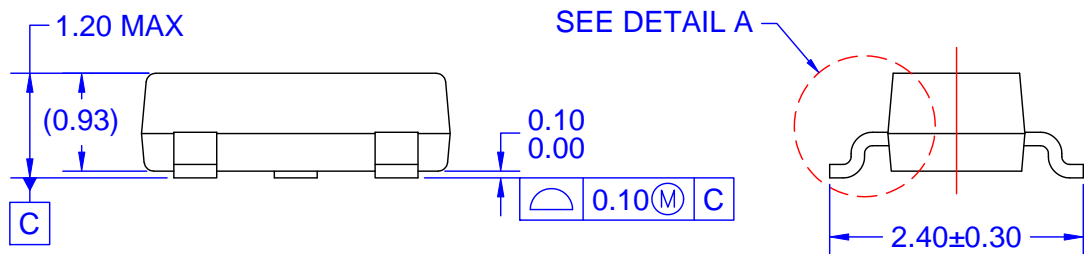


Figure 6. Current Gain Bandwidth Product



**DETAIL A**  
SCALE: 2X






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